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## CENTRAL LOCATION

### FACSIMILE COVER SHEET

**Examiner:** Sikyin Ip **Group:** 1742  
**Date:** April 12, 2007  
**Client Code:** 2678  
**Facsimile No.:** 571-273-1241  
**From:** Darrell L. Wong, Esq.

**Subject:** Proposed Claim Amendments

**Docket No.:** 2678.2011-000

**Applicant:** Premakaran T. Boaz, *et al*

**Application No.:** 10/802,387

**Filing Date:** March 17, 2004

Number of pages including this cover sheet: 2

Please confirm receipt of facsimile: Yes ☒ No ☐

### Comments:

**Dear Examiner IP,**

**As we discussed, please find attached proposed amended claims 1 and 16.  
Please let me know what is a good time for you for a telephone interview.**

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## PROPOSED CLAIM AMENDMENTS

1. (Amended) A solder composition comprising:  
    ~~a mixture of elements~~ an alloy comprising tin (Sn) and silver (Ag); and  
    a granular additive which is at least about 3% of the solder composition by weight, the granular additive comprising a nickel iron alloy comprising about 36% nickel (Ni) and about 64% iron (Fe) , by weight, the granular additive being in granular form within said alloy.
  
16. (Amended) A solder composition comprising:  
    ~~a mixture of elements~~ an alloy comprising tin and silver; and  
    a granular additive comprising a material having a low coefficient of thermal expansion and being at least about 3% of the solder composition by weight, the granular additive being in granular form in said alloy.

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